

E¹
cont a cassette stage for mounting a cassette having wafers stacked thereon;

a transfer path adjacent to the cassette stage for providing space for transportation of wafers, the transfer path being at atmospheric pressure and having a width slightly larger than a diameter of the wafers;

a plurality of processing chambers aligned in a plurality of layers parallel to and beside the transfer path;

a transfer mechanism capable of vertical/horizontal reciprocal movement installed in the transfer path for loading and unloading the wafers stacked on the cassette stage; and

a load lock chamber connected to one side of the processing chambers, the load lock chamber serving as a stand-by area for the wafers.

22
~~24~~ (Twice Amended) The multi-chamber system of an etching facility for manufacturing semiconductor devices according to claim ~~20~~¹⁹, wherein the load lock chamber comprises:

E² a transfer arm for receiving wafers from the transfer mechanism and transferring the wafers to the processing chambers;

an inner transfer device for moving the transfer arm; and

gates formed on a side of the transfer path and sides of the processing chambers, respectively, the gates being selectively opened and closed to allow passage of the wafers.